

HAT2088R

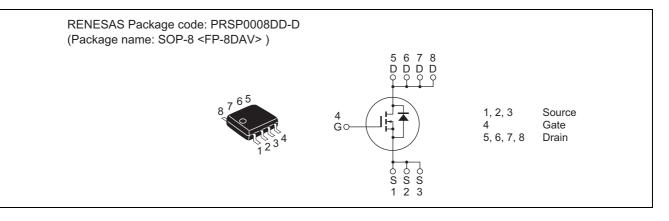
Silicon N Channel MOS FET High Speed Power Switching

> REJ03G1183-0200 (Previous: ADE-208-1234) Rev.2.00 Sep 07, 2005

Features

- Low on-resistance
- www.DataSheet U.Low leakage current
 - High density mounting

Outline





Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
ltem	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	200	V
Gate to source voltage	V _{GSS}	±30	V
Drain current	ID	2	A
Drain peak current	I _{D (pulse)} Note 1	16	A
Body-drain diode reverse drain current	I _{DR}	2	A
Channel dissipation	Pch Note 2	2.5	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

www.DataSheet4U.com 2. When using the glass epoxy board (FR4 $40 \times 40 \times 1.6$ mm), PW ≤ 10 s

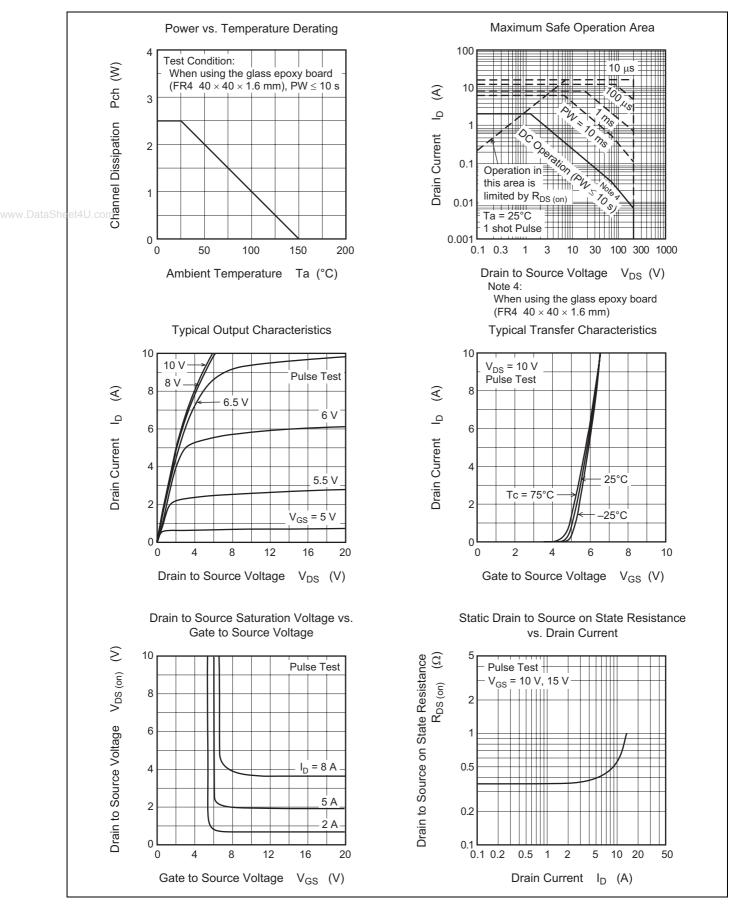
Electrical Characteristics

						$(Ta = 25^{\circ}C)$
ltem	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V (BR) DSS	200			V	$I_{D} = 10 \text{ mA}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	—	_	±0.1	μA	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	—	_	1	μA	$V_{DS} = 200 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	3.0	_	4.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Static drain to source on state resistance	R _{DS (on)}	—	0.35	0.44	Ω	$I_D = 1 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note 3}}$
Forward transfer admittance	y _{fs}	1.5	2.5		S	$I_D = 1 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note 3}}$
Input capacitance	Ciss	—	450		pF	$V_{DS} = 25 \text{ V}, V_{GS} = 0$
Output capacitance	Coss	—	65		pF	f = 1 MHz
Reverse transfer capacitance	Crss	—	13		pF	
Total gate charge	Qg	—	13		nC	V _{DD} = 160 V
Gate to source charge	Qgs	—	2		nC	V _{GS} = 10 V
Gate to drain charge	Qgd	—	6		nC	$I_D = 2 A$
Turn-on delay time	t _{d (on)}	—	19		ns	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ A}$
Rise time	tr	—	8.5	_	ns	$V_{DD} \cong 100 \text{ V}$
Turn-off delay time	t _{d (off)}	—	48		ns	$R_L = 100 \Omega$
Fall time	t _f	—	11	—	ns	Rg = 10 Ω
Body-drain diode forward voltage	V _{DF}	_	0.8	1.2	V	$I_F = 2 \text{ A}, V_{GS} = 0^{\text{Note 3}}$
Body-drain diode reverse recovery time	t _{rr}	_	65		ns	$I_F = 2 A, V_{GS} = 0$
						di _F /dt = 100 A/µs

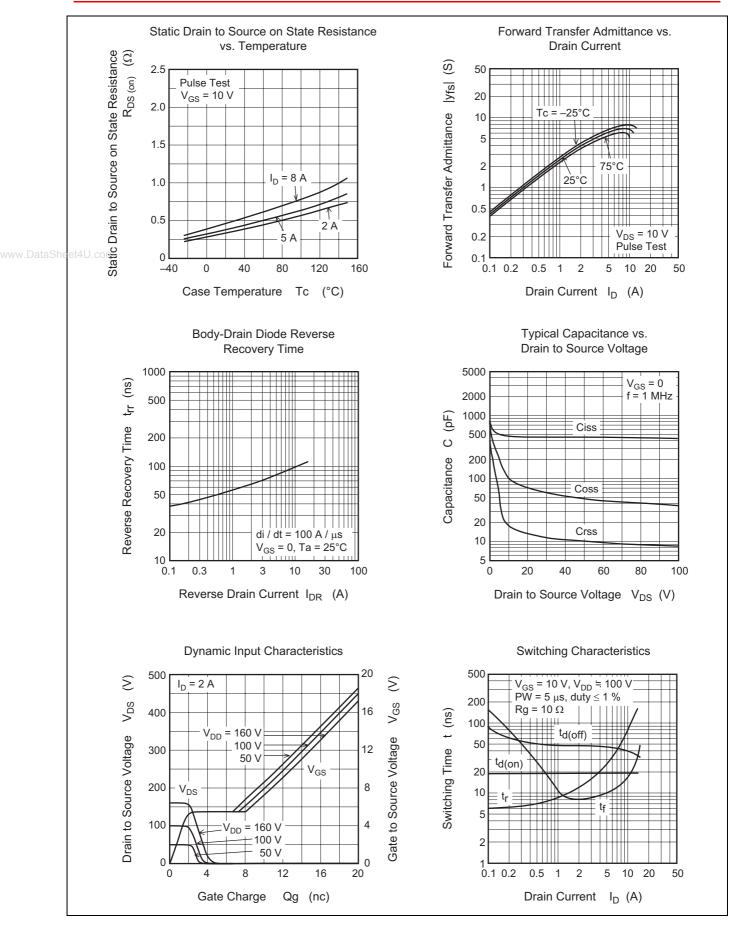
Note: 3. Pulse test



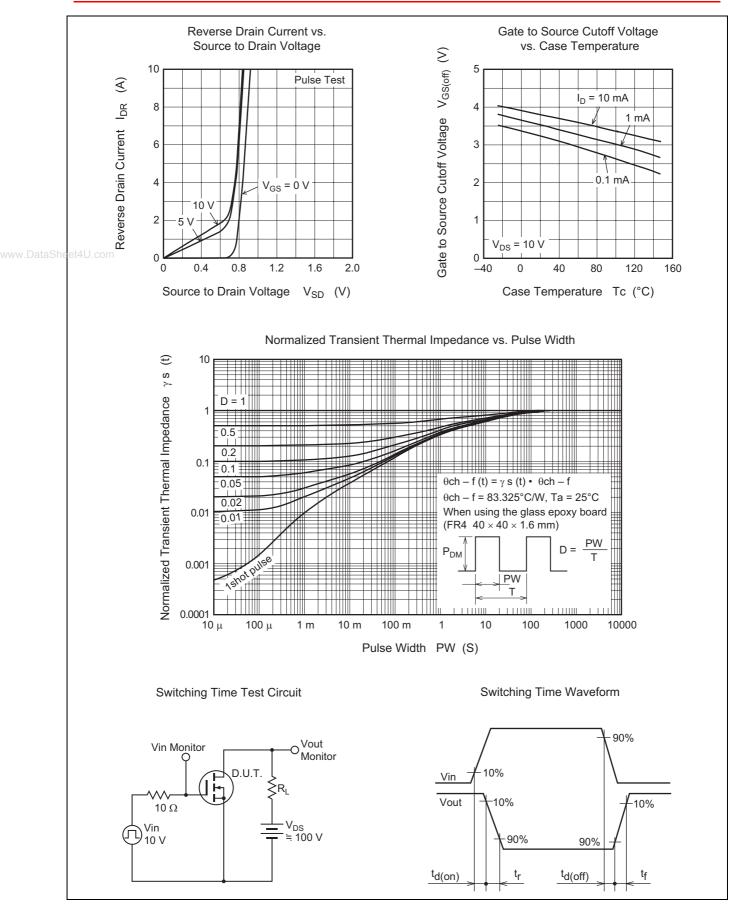
Main Characteristics



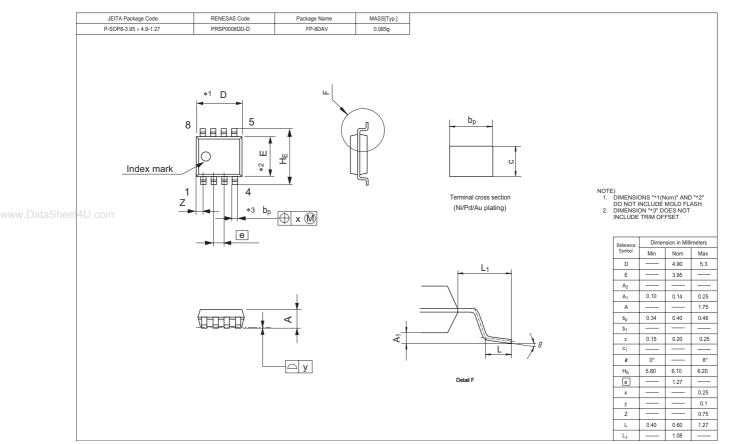








Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT2088R-EL-E	2500 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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